



COPPER TIN ALLOY PLATING PRODUCT



Commodity Name

HN-BS BRIGHT WHITE COPPER TIN PLATING PROCESS



Bath Composition and Working Conditions

	Rack Plating	Barrel Plating
CuCN	9 ~ 12g/l	9 ~ 12g/l
NaCN	45 ~ 55g/l	45 ~ 55g/l
Na ₂ SnO ₃	50 ~ 60g/l	50 ~ 60g/l
NaOH	15 ~ 18g/l	15 ~ 18g/l
KNaC ₄ H ₄ O ₆ · 4H ₂ O	130 ~ 150g/l	130 ~ 150g/l
HN-BSA	3 ~ 4ml/l	3 ~ 4ml/l
HN-BSB	4 ~ 5ml/l	4 ~ 5ml/l
Temperature	60 ~ 70°C	50 ~ 60°C
Cathode Current Density	0.7 ~ 1.2 A/dm ²	0.7 ~ 1.2 A/dm ²
Anode	Graphite panel	Graphite panel
Filtration	Recycling filtration	
HN-BSA	White Copper Tin Brightener	
HN-BSB	White Copper Tin Additive	



Application and Advantage

- 1.The plating speed is quite fast, and the layer thickness in high potential region is uniform, the brightness is in consistency.
- 2.The adhesion between the coating and the base materials is good.
- 3.The plating coating is flexible without pinholes and pits. The anti-corrosion is good.
- 4.The process is stable and is easy to operate and control.
- 5.This process is free of zinc, and the soldering performance is good.



★★★★★
广东高力集团
HIGHNIC GROUP



广东致卓精密金属科技有限公司
SUR-PRECISION METAL TECHNOLOGY CO., LTD.

- Production Base : Central Part of Non-ferrous Metal Industrial Development Zone, Shishan, Nanhai, Foshan, Guangdong, China
- Sales Center : Highnic Group Building, Guangfo Rd., Yanbu, Dali Town, Nanhai District, Foshan City, Guangdong Province, China.
- Mail: sale@imt-pcb.com Fax : (86-757) 85768678 Tel : (86-757) 85728852